

(43) International Publication Date
14 July 2011 (14.07.2011)(10) International Publication Number
WO 2011/084235 A2(51) International Patent Classification:
H01L 23/485 (2006.01) **H01L 21/60** (2006.01)**na M.**; 19815 N. 84th Way, Scottsdale, Arizona 85255 (US).(21) International Application Number:
PCT/US2010/056310(74) Agents: **VINCENT, Lester J.** et al.; Blakely Sokoloff Taylor & Zafman, 1279 Oakmead Parkway, Sunnyvale, California 94085 (US).(22) International Filing Date:
11 November 2010 (11.11.2010)

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/653,710 17 December 2009 (17.12.2009) US(71) Applicant (for all designated States except US): **INTEL CORPORATION**; 2200 Mission College Boulevard, MS: RNB-4-150, Santa Clara, California 95052 (US).

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(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU,

[Continued on next page]

(54) Title: GLASS CORE SUBSTRATE FOR INTEGRATED CIRCUIT DEVICES AND METHODS OF MAKING THE SAME

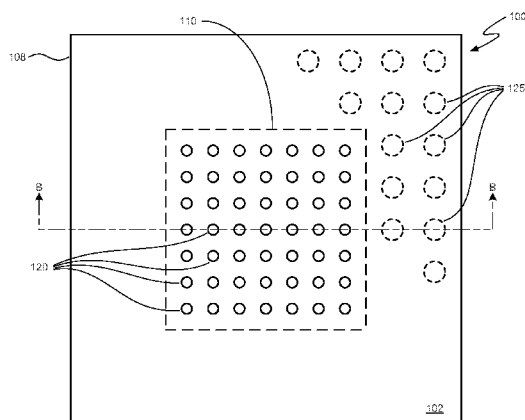


FIG. 1A

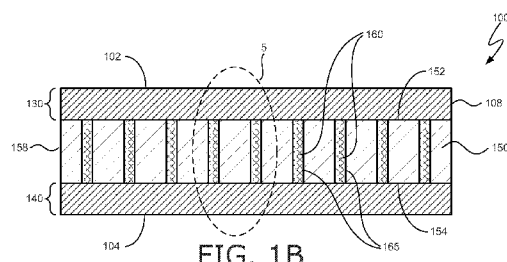


FIG. 1B

(57) Abstract: Disclosed are embodiments of a glass core substrate for an integrated circuit (IC) device. The glass core substrate includes a glass core and build-up structures on opposing sides of the glass core. Electrically conductive terminals may be formed on both sides of the glass core substrate. An IC die may be coupled with the terminals on one side of the substrate, whereas the terminals on the opposing side may be coupled with a next-level component, such as a circuit board. The glass core may comprise a single piece of glass in which conductors have been formed, or the glass core may comprise two or more glass sections that have been joined together, each section having conductors. The conductors extend through the glass core, and one or more of the conductors may be electrically coupled with the build-up structures disposed over the glass core. Other embodiments are described and claimed.



LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, **Published:**

SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,

GW, ML, MR, NE, SN, TD, TG).

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